

256K-BIT CMOS STATIC RAM  
 32K-WORD BY 8-BIT

**Description**

The  $\mu$ PD43256B is a high speed, low power, and 262,144 bits (32,768 words by 8 bits) CMOS static RAM. Battery backup is available. And A and B versions are wide voltage operations. The  $\mu$ PD43256B is packed in 28-pin plastic DIP, 28-pin plastic SOP and 28-pin plastic TSOP (I) (8 x 13.4 mm).

**Features**

- 32,768 words by 8 bits organization
- Fast access time: 70, 85, 100, 120, 150 ns (MAX.)
- Low voltage operation (A version:  $V_{CC} = 3.0$  to 5.5 V, B version:  $V_{CC} = 2.7$  to 5.5 V)
- Low  $V_{CC}$  data retention: 2.0 V (MIN.)
- /OE input for easy application

Part number	Access time ns (MAX.)	Operating supply voltage V	Operating ambient temperature °C	Supply current		
				At operating mA (MAX.)	At standby $\mu$ A (MAX.)	At data retention $\mu$ A (MAX.) <sup>Note1</sup>
$\mu$ PD43256B-xxL	70, 85	4.5 to 5.5	0 to 70	45	50	3
$\mu$ PD43256B-xxLL					15	2
$\mu$ PD43256B-Axx	85, 100 <sup>Note2</sup> , 120 <sup>Note2</sup>	3.0 to 5.5				
$\mu$ PD43256B-Bxx <sup>Note2</sup>	100, 120, 150	2.7 to 5.5				

- Notes 1.**  $T_A \leq 40$  °C,  $V_{CC} = 3.0$  V  
**2.** Access time: 85 ns (MAX.) ( $V_{CC} = 4.5$  to 5.5 V)

**Version X and P**

This Data sheet can be applied to the version X and P. Each version is identified with its lot number. Letter X in the fifth character position in a lot number signifies version X, letter P, version P.



The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version. Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

Ordering Information

Part number	Package	Access time ns (MAX.)	Operating supply voltage V	Operating ambient temperature °C	Remark	
μPD43256BCZ-70L	28-PIN PLASTIC DIP (15.24 mm (600))	70	4.5 to 5.5	0 to 70	L version	
μPD43256BCZ-85L		85				
μPD43256BCZ-70LL		70			LL version	
μPD43256BCZ-85LL		85				
μPD43256BGU-70L	28-PIN PLASTIC SOP (11.43 mm (450))	70	3.0 to 5.5	0 to 70	L version	
μPD43256BGU-85L		85				
μPD43256BGU-70LL		70			LL version	
μPD43256BGU-85LL		85				
μPD43256BGU-A85		85	2.7 to 5.5	0 to 70	A version	
μPD43256BGU-A10		100				
μPD43256BGU-A12		120				
μPD43256BGU-B10		100			B version	
μPD43256BGU-B12		120				
μPD43256BGW-70LL-9JL	28-PIN PLASTIC TSOP (I) (8x13.4) (Normal bent)	70	4.5 to 5.5	0 to 70	LL version	
μPD43256BGW-85LL-9JL		85				
μPD43256BGW-A85-9JL		85			3.0 to 5.5	A version
μPD43256BGW-A10-9JL		100				
μPD43256BGW-A12-9JL		120				
μPD43256BGW-B10-9JL		100	2.7 to 5.5	0 to 70	B version	
μPD43256BGW-B12-9JL		120				
μPD43256BGW-B15-9JL		150				
μPD43256BGW-70LL-9KL	28-PIN PLASTIC TSOP (I) (8x13.4) (Reverse bent)	70	4.5 to 5.5	0 to 70	LL version	
μPD43256BGW-85LL-9KL		85				
μPD43256BGW-A85-9KL		85			3.0 to 5.5	A version
μPD43256BGW-A10-9KL		100				
μPD43256BGW-A12-9KL		120				
μPD43256BGW-B10-9KL		100	2.7 to 5.5	0 to 70	B version	
μPD43256BGW-B12-9KL		120				
μPD43256BGW-B15-9KL		150				

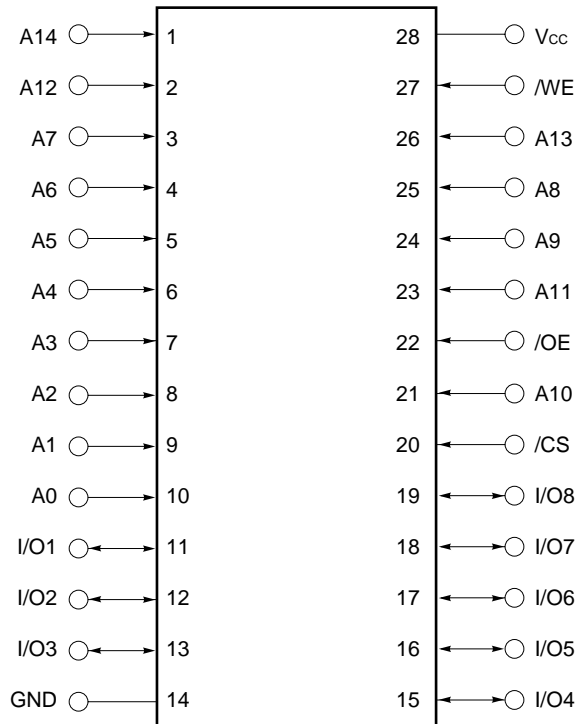
**Pin Configurations (Marking Side)**

/xxx indicates active low signal.

**28-PIN PLASTIC DIP (15.24 mm (600))**

[ μPD43256BCZ-xxL ]

[ μPD43256BCZ-xxLL ]



- A0 - A14 : Address inputs
- I/O1 - I/O8 : Data inputs / outputs
- /CS : Chip Select
- /WE : Write Enable
- /OE : Output Enable
- Vcc : Power supply
- GND : Ground

**Remark** Refer to **Package Drawings** for the 1-pin index mark.

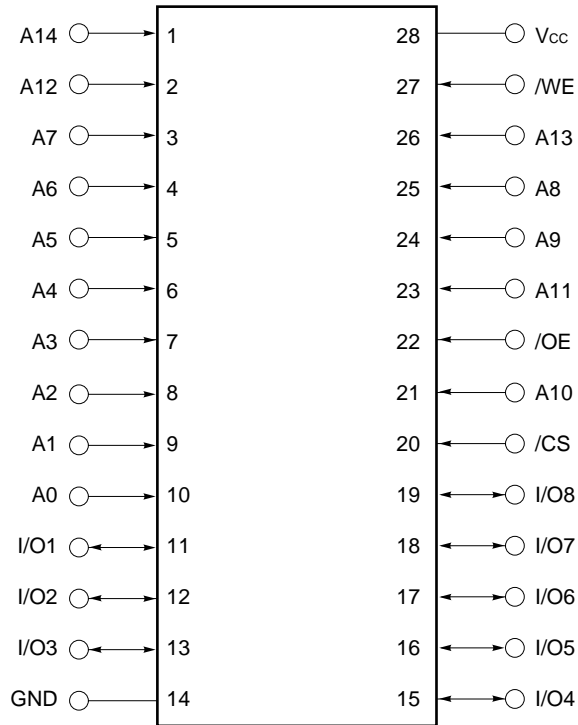
28-PIN PLASTIC SOP (11.43 mm (450))

[ μPD43256BGU-xxL ]

[ μPD43256BGU-xxLL ]

[ μPD43256BGU-Axx ]

[ μPD43256BGU-Bxx ]



- A0 - A14 : Address inputs
- I/O1 - I/O8 : Data inputs / outputs
- /CS : Chip Select
- /WE : Write Enable
- /OE : Output Enable
- Vcc : Power supply
- GND : Ground

**Remark** Refer to **Package Drawings** for the 1-pin index mark.

28-PIN PLASTIC TSOP (I) (8x13.4) (Normal bent)

[ μPD43256BGW-xxLL-9JL ]

[ μPD43256BGW-Axx-9JL ]

[ μPD43256BGW-Bxx-9JL ]



28-PIN PLASTIC TSOP (I) (8x13.4) (Reverse bent)

[ μPD43256BGW-xxLL-9KL ]

[ μPD43256BGW-Axx-9KL ]

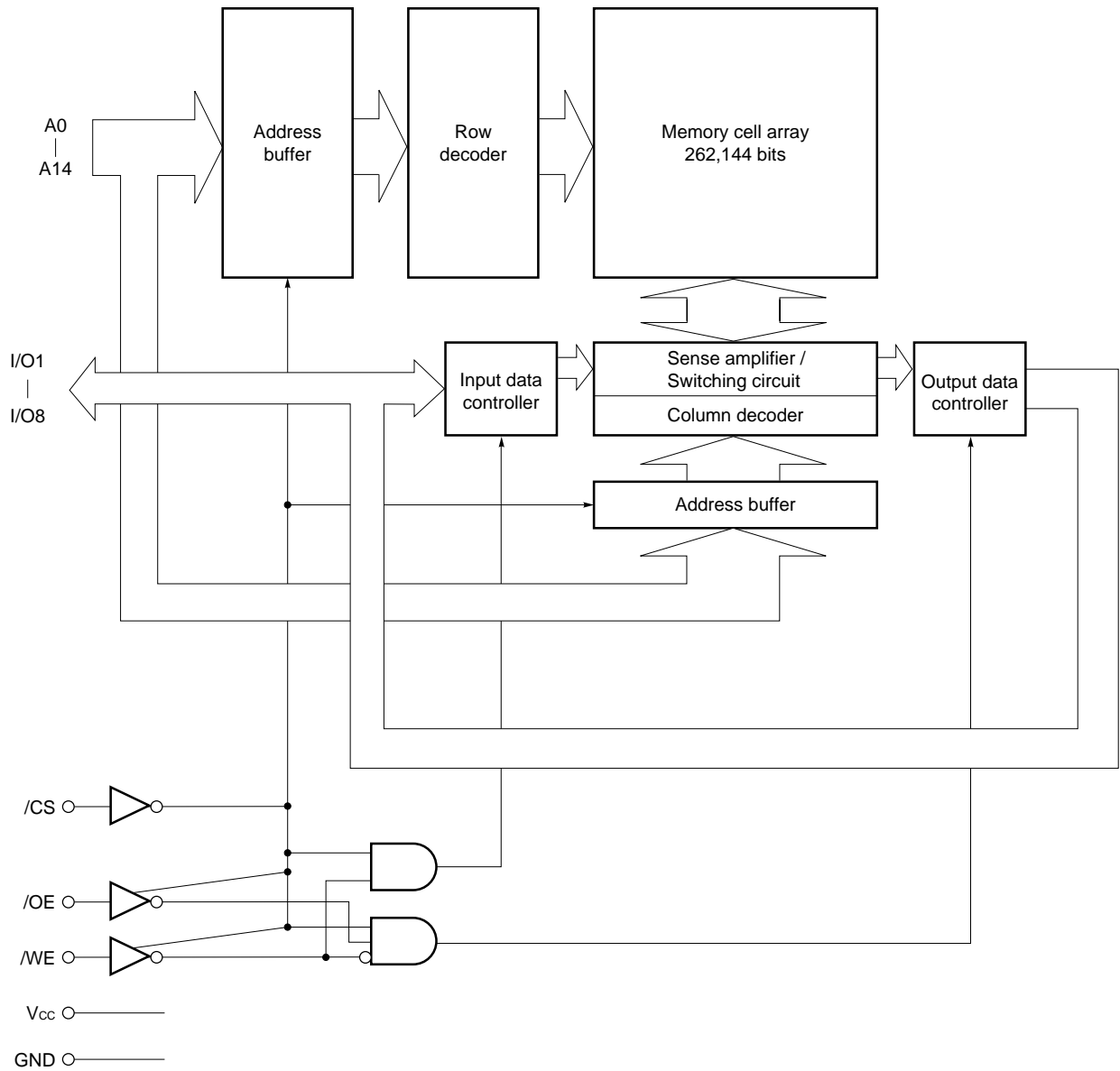
[ μPD43256BGW-Bxx-9KL ]



- A0 - A14 : Address inputs
- I/O1 - I/O8 : Data inputs / outputs
- /CS : Chip Select
- /WE : Write Enable
- /OE : Output Enable
- Vcc : Power supply
- GND : Ground

**Remark** Refer to **Package Drawings** for the 1-pin index mark.

Block Diagram



Truth Table

/CS	/OE	/WE	Mode	I/O	Supply current
H	x	x	Not selected	High impedance	I <sub>SB</sub>
L	H	H	Output disable		I <sub>CCA</sub>
L	x	L	Write	D <sub>IN</sub>	
L	L	H	Read	D <sub>OUT</sub>	

Remark x : V<sub>IH</sub> or V<sub>IL</sub>

**Electrical Specifications**

**Absolute Maximum Ratings**

Parameter	Symbol	Condition	Rating	Unit
Supply voltage	V <sub>CC</sub>		-0.5 <sup>Note</sup> to +7.0	V
Input / Output voltage	V <sub>T</sub>		-0.5 <sup>Note</sup> to V <sub>CC</sub> + 0.5	V
Operating ambient temperature	T <sub>A</sub>		0 to 70	°C
Storage temperature	T <sub>stg</sub>		-55 to +125	°C

**Note** -3.0 V (MIN.) (Pulse width : 50 ns)

**Caution** Exposing the device to stress above those listed in Absolute Maximum Rating could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

**Recommended Operating Conditions**

Parameter	Symbol	Condition	μPD43256B-xxL		μPD43256B-Axx		μPD43256B-Bxx		Unit
			μPD43256B-xxLL		MIN.	MAX.	MIN.	MAX.	
			MIN.	MAX.					
Supply voltage	V <sub>CC</sub>		4.5	5.5	3.0	5.5	2.7	5.5	V
High level input voltage	V <sub>IH</sub>		2.2	V <sub>CC</sub> +0.5	2.2	V <sub>CC</sub> +0.5	2.2	V <sub>CC</sub> +0.5	V
Low level input voltage	V <sub>IL</sub>		-0.3 <sup>Note</sup>	+0.8	-0.3 <sup>Note</sup>	+0.5	-0.3 <sup>Note</sup>	+0.5	V
Operating ambient temperature	T <sub>A</sub>		0	70	0	70	0	70	°C

**Note** -3.0 V (MIN.) (Pulse width: 50 ns)

**Capacitance (T<sub>A</sub> = 25 °C, f = 1 MHz)**

Parameter	Symbol	Test conditions	MIN.	TYP.	MAX.	Unit
Input capacitance	C <sub>IN</sub>	V <sub>IN</sub> = 0 V			5	pF
Input / Output capacitance	C <sub>I/O</sub>	V <sub>I/O</sub> = 0 V			8	pF

**Remarks** 1. V<sub>IN</sub> : Input voltage

V<sub>I/O</sub> : Input / Output voltage

2. These parameters are periodically sampled and not 100% tested.

DC Characteristics (Recommended Operating Conditions Unless Otherwise Noted) (1/2)

Parameter	Symbol	Test condition	μPD43256B-xxL			μPD43256B-xxLL			Unit
			MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Input leakage current	I <sub>LI</sub>	V <sub>IN</sub> = 0 V to V <sub>CC</sub>	-1.0		+1.0	-1.0		+1.0	μA
I/O leakage current	I <sub>LO</sub>	V <sub>I/O</sub> = 0 V to V <sub>CC</sub> , /OE = V <sub>IH</sub> or /CS = V <sub>IH</sub> or /WE = V <sub>IL</sub>	-1.0		+1.0	-1.0		+1.0	μA
Operating supply current	I <sub>CCA1</sub>	/CS = V <sub>IL</sub> , Minimum cycle time, I <sub>I/O</sub> = 0 mA			45			45	mA
	I <sub>CCA2</sub>	/CS = V <sub>IL</sub> , I <sub>I/O</sub> = 0 mA			10			10	
	I <sub>CCA3</sub>	/CS ≤ 0.2 V, Cycle = 1 MHz, I <sub>I/O</sub> = 0 mA, V <sub>IL</sub> ≤ 0.2 V, V <sub>IH</sub> ≥ V <sub>CC</sub> - 0.2 V			10			10	
Standby supply current	I <sub>SB</sub>	/CS = V <sub>IH</sub>			3			3	mA
	I <sub>SB1</sub>	/CS ≥ V <sub>CC</sub> - 0.2 V		1.0	50		0.5	15	
High level output voltage	V <sub>OH1</sub>	I <sub>OH</sub> = -1.0 mA	2.4			2.4			V
	V <sub>OH2</sub>	I <sub>OH</sub> = -0.1 mA	V <sub>CC</sub> -0.5			V <sub>CC</sub> -0.5			
Low level output voltage	V <sub>OL</sub>	I <sub>OL</sub> = 2.1 mA			0.4			0.4	V

Remarks 1. V<sub>IN</sub> : Input voltage

V<sub>I/O</sub> : Input / Output voltage

2. These DC characteristics are in common regardless of package types.



DC Characteristics (Recommended Operating Conditions Unless Otherwise Noted) (2/2)

Parameter	Symbol	Test condition	μPD43256B-Axx			μPD43256B-Bxx			Unit
			MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Input leakage current	I <sub>LI</sub>	V <sub>IN</sub> = 0 V to V <sub>CC</sub>	-1.0		+1.0	-1.0		+1.0	μA
I/O leakage current	I <sub>LO</sub>	V <sub>I/O</sub> = 0 V to V <sub>CC</sub> , /OE = V <sub>IH</sub> or /CS = V <sub>IH</sub> or /WE = V <sub>IL</sub>	-1.0		+1.0	-1.0		+1.0	μA
Operating supply current	I <sub>CCA1</sub>	/CS = V <sub>IL</sub> , Minimum cycle time, I <sub>I/O</sub> = 0 mA	μPD43256B-Axx		45			-	mA
			μPD43256B-Bxx				-	45	
			V <sub>CC</sub> ≤ 3.3 V				-	20	
	I <sub>CCA2</sub>	/CS = V <sub>IL</sub> , I <sub>I/O</sub> = 0 mA			10			10	
			V <sub>CC</sub> ≤ 3.3 V				-	5	
	I <sub>CCA3</sub>	/CS ≤ 0.2 V, Cycle = 1 MHz, I <sub>I/O</sub> = 0 mA, V <sub>IL</sub> ≤ 0.2 V, V <sub>IH</sub> ≥ V <sub>CC</sub> - 0.2 V			10			10	
V <sub>CC</sub> ≤ 3.3 V					-	5			
Standby supply current	I <sub>SB</sub>	/CS = V <sub>IH</sub>			3			3	mA
			V <sub>CC</sub> ≤ 3.3 V				-	2	
	I <sub>SB1</sub>	/CS ≥ V <sub>CC</sub> - 0.2 V			0.5	15	0.5	15	μA
			V <sub>CC</sub> ≤ 3.3 V				-	0.5	
High level output voltage	V <sub>OH1</sub>	I <sub>OH</sub> = -1.0 mA, V <sub>CC</sub> ≥ 4.5 V	2.4			2.4			V
		I <sub>OH</sub> = -0.5 mA, V <sub>CC</sub> < 4.5 V	2.4			2.4			
	V <sub>OH2</sub>	I <sub>OH</sub> = -0.02 mA	V <sub>CC</sub> -0.1			V <sub>CC</sub> -0.1			
Low level output voltage	V <sub>OL</sub>	I <sub>OL</sub> = 2.1 mA, V <sub>CC</sub> ≥ 4.5 V			0.4			0.4	V
		I <sub>OL</sub> = 1.0 mA, V <sub>CC</sub> < 4.5 V			0.4			0.4	
	V <sub>OL1</sub>	I <sub>OL</sub> = 0.02 mA			0.1			0.1	

Remarks 1. V<sub>IN</sub> : Input voltage

V<sub>I/O</sub> : Input / Output voltage

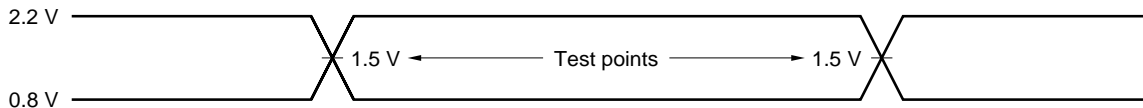
2. These DC characteristics are in common regardless of package types.

AC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)

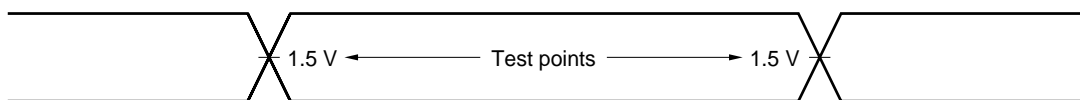
AC Test Conditions

[ μPD43256B-70L, μPD43256B-85L, μPD43256B-70LL, μPD43256B-85LL ]

Input Waveform (Rise and Fall Time ≤ 5 ns)



Output Waveform



Output Load

AC characteristics should be measured with the following output load conditions.

Figure 1

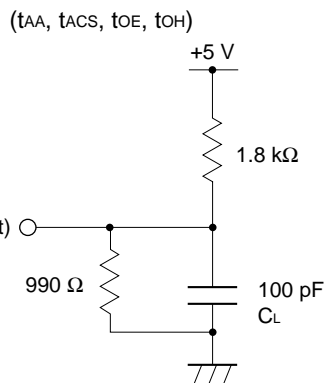
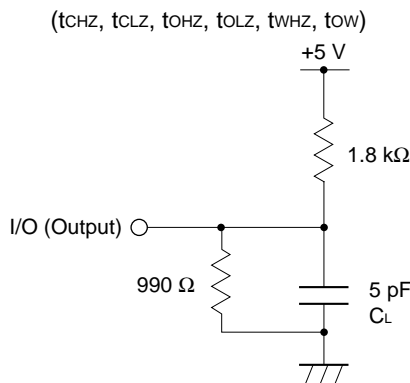


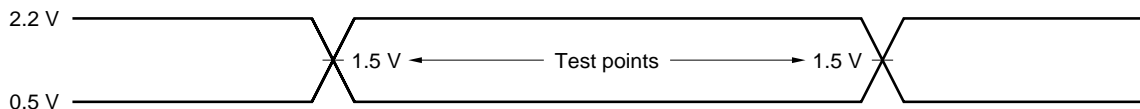
Figure 2



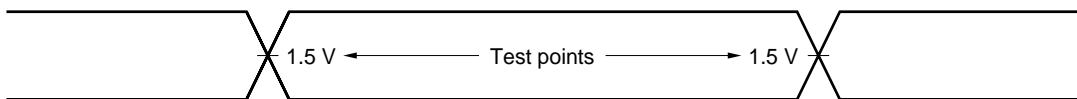
Remark CL includes capacitance of the probe and jig, and stray capacitance.

[ μPD43256B-A85, μPD43256B-A10, μPD43256B-A12, μPD43256B-B10, μPD43256B-B12, μPD43256B-B15 ]

Input Waveform (Rise and Fall Time ≤ 5 ns)



Output Waveform



Output Load

AC characteristics should be measured with the following output load conditions.

tAA, tACS, tOE, tOH	tCHZ, tCLZ, tOHZ, tOLZ, tWHZ, tOW
1TTL + 100 pF	1TTL + 5 pF

**Read Cycle (1/2)**

Parameter	Symbol	V <sub>CC</sub> ≥ 4.5 V				Unit	Condition
		μPD43256B-70		μPD43256B-85			
		MIN.	MAX.	MIN.	MAX.		
Read cycle time	t <sub>RC</sub>	70		85		ns	
Address access time	t <sub>AA</sub>		70		85	ns	<b>Note</b>
/CS access time	t <sub>ACS</sub>		70		85	ns	
/OE access time	t <sub>OE</sub>		35		40	ns	
Output hold from address change	t <sub>OH</sub>	10		10		ns	
/CS to output in low impedance	t <sub>CLZ</sub>	10		10		ns	
/OE to output in low impedance	t <sub>OLZ</sub>	5		5		ns	
/CS to output in high impedance	t <sub>CHZ</sub>		30		30	ns	
/OE to output in high impedance	t <sub>OHZ</sub>		30		30	ns	

**Note** See the **output load**.

**Remark** These AC characteristics are in common regardless of package types and L, LL versions.

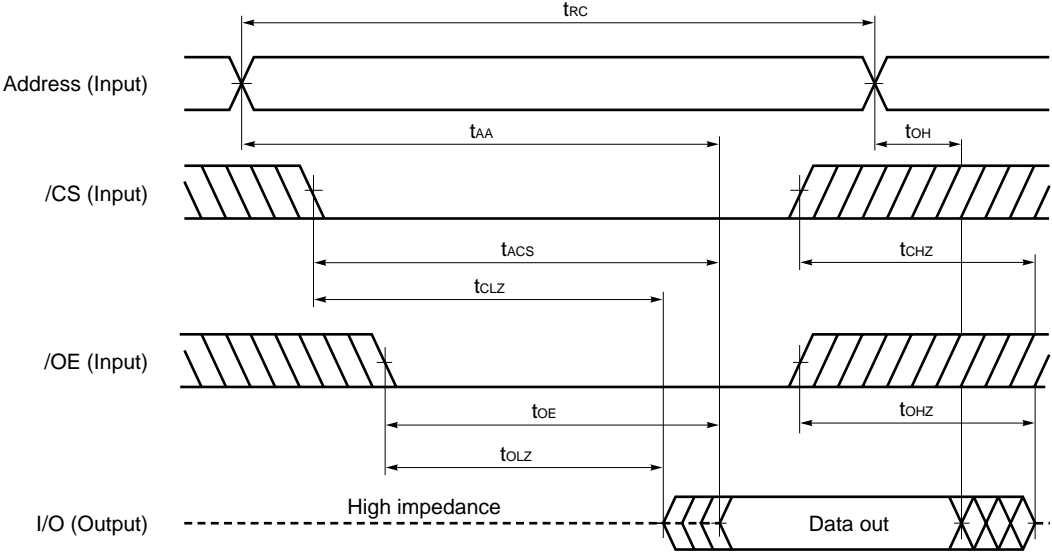
**Read Cycle (2/2)**

Parameter	Symbol	V <sub>CC</sub> ≥ 3.0 V						V <sub>CC</sub> ≥ 2.7 V						Unit	Con- dition
		μPD43256B -A85		μPD43256B -A10		μPD43256B -A12		μPD43256B -B10		μPD43256B -B12		μPD43256B -B15			
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read cycle time	t <sub>RC</sub>	85		100		120		100		120		150		ns	
Address access time	t <sub>AA</sub>		85		100		120		100		120		150	ns	<b>Note</b>
/CS access time	t <sub>ACS</sub>		85		100		120		100		120		150	ns	
/OE access time	t <sub>OE</sub>		50		60		60		60		60		70	ns	
Output hold from address change	t <sub>OH</sub>	10		10		10		10		10		10		ns	
/CS to output in low impedance	t <sub>CLZ</sub>	10		10		10		10		10		10		ns	
/OE to output in low impedance	t <sub>OLZ</sub>	5		5		5		5		5		5		ns	
/CS to output in high impedance	t <sub>CHZ</sub>		35		35		40		35		40		50	ns	
/OE to output in high impedance	t <sub>OHZ</sub>		35		35		40		35		40		50	ns	

**Note** See the **output load**.

**Remark** These AC characteristics are in common regardless of package types.

Read Cycle Timing Chart



**Remark** In read cycle, /WE should be fixed to high level.

**Write Cycle (1/2)**

Parameter	Symbol	V <sub>CC</sub> ≥ 4.5 V				Unit	Condition
		μPD43256B-70		μPD43256B-85 μPD43256B-A85/A10/A12 μPD43256B-B10/B12/B15			
		MIN.	MAX.	MIN.	MAX.		
Write cycle time	t <sub>WC</sub>	70		85		ns	
/CS to end of write	t <sub>CW</sub>	50		70		ns	
Address valid to end of write	t <sub>AW</sub>	50		70		ns	
Write pulse width	t <sub>WP</sub>	55		60		ns	
Data valid to end of write	t <sub>DW</sub>	30		35		ns	
Data hold time	t <sub>DH</sub>	0		0		ns	
Address setup time	t <sub>AS</sub>	0		0		ns	
Write recovery time	t <sub>WR</sub>	0		0		ns	
/WE to output in high impedance	t <sub>WHZ</sub>		30		30	ns	<b>Note</b>
Output active from end of write	t <sub>OW</sub>	10		10		ns	

**Note** See the **output load**.

**Remark** These AC characteristics are in common regardless of package types and L, LL versions.

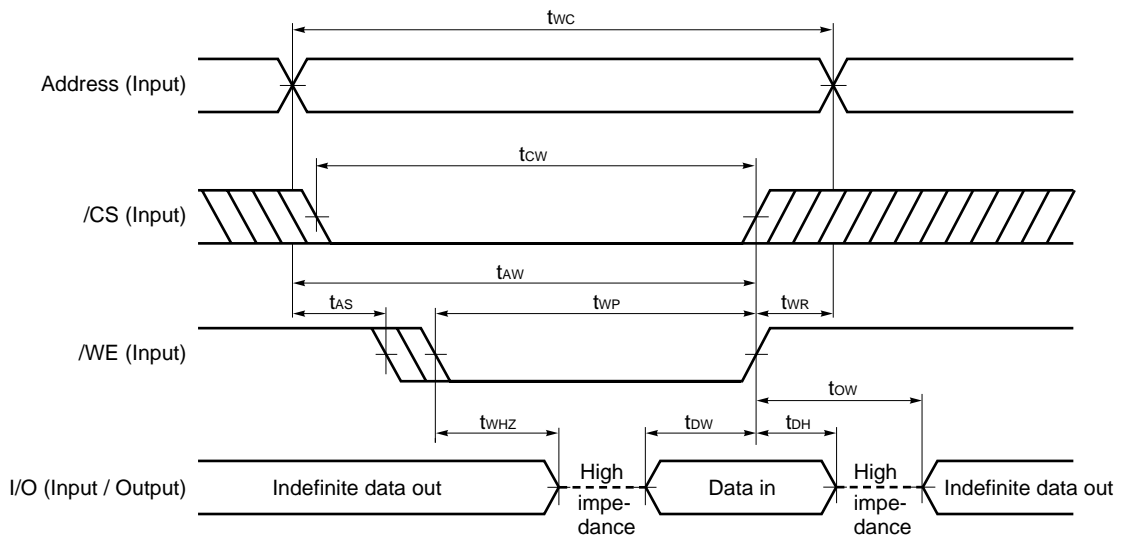
**Write Cycle (2/2)**

Parameter	Symbol	V <sub>CC</sub> ≥ 3.0 V						V <sub>CC</sub> ≥ 2.7 V						Unit	Con- dition
		μPD43256B -A85		μPD43256B -A10		μPD43256B -A12		μPD43256B -B10		μPD43256B -B12		μPD43256B -B15			
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Write cycle time	t <sub>WC</sub>	85		100		120		100		120		150		ns	
/CS to end of write	t <sub>CW</sub>	70		70		90		70		90		100		ns	
Address valid to end of write	t <sub>AW</sub>	70		70		90		70		90		100		ns	
Write pulse width	t <sub>WP</sub>	60		60		80		60		80		90		ns	
Data valid to end of write	t <sub>DW</sub>	60		60		70		60		70		80		ns	
Data hold time	t <sub>DH</sub>	0		0		0		0		0		0		ns	
Address setup	t <sub>AS</sub>	0		0		0		0		0		0		ns	
Write recovery	t <sub>WR</sub>	0		0		0		0		0		0		ns	
/WE to output in high impedance	t <sub>WHZ</sub>		30		35		40		35		40		50	ns	<b>Note</b>
Output active from end of write	t <sub>OW</sub>	10		10		10		10		10		10		ns	

**Note** See the **output load**.

**Remark** These AC characteristics are in common regardless of package types.

**Write Cycle Timing Chart 1 (/WE Controlled)**



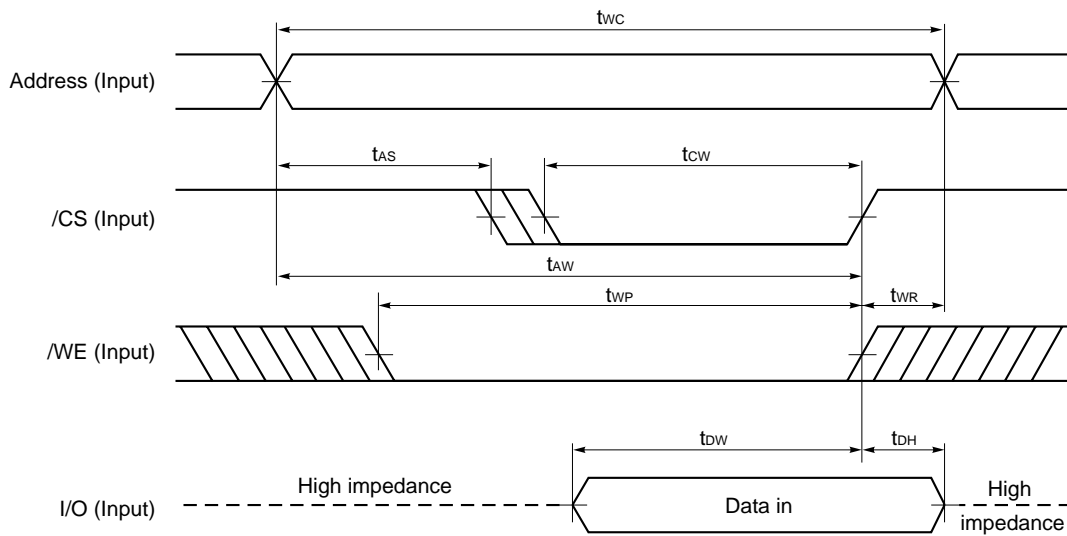
**Cautions 1.** /CS or /WE should be fixed to high level during address transition.

- ★ **2.** When I/O pins are in the output state, therefore the input signals must not be applied to the output.

**Remarks 1.** Write operation is done during the overlap time of a low level /CS and a low level /WE.

- 2.** When /WE is at low level, the I/O pins are always high impedance. When /WE is at high level, read operation is executed. Therefore /OE should be at high level to make the I/O pins high impedance.
- 3.** If /CS changes to low level at the same time or after the change of /WE to low level, the I/O pins will remain high impedance state.

**Write Cycle Timing Chart 2 (/CS Controlled)**



**Cautions 1. /CS or /WE should be fixed to high level during address transition.**

- ★ **2. When I/O pins are in the output state, therefore the input signals must not be applied to the output.**

**Remark** Write operation is done during the overlap time of a low level /CS and a low level /WE.

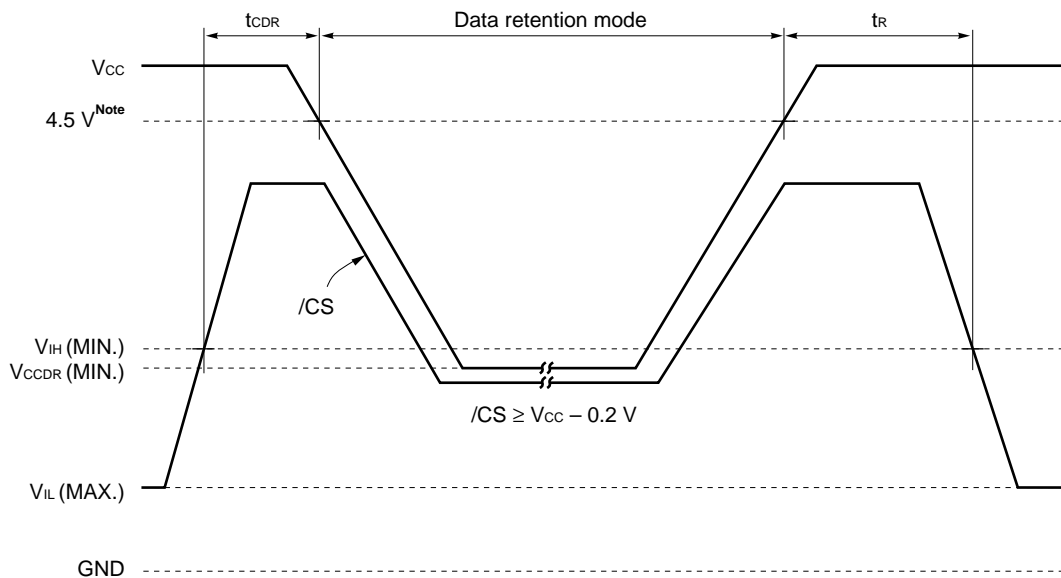
**Low V<sub>CC</sub> Data Retention Characteristics (T<sub>A</sub> = 0 to 70 °C)**

Parameter	Symbol	Test Condition	μPD43256B-xxL			μPD43256B-xxLL μPD43256B-Axx μPD43256B-Bxx			Unit
			MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Data retention supply voltage	V <sub>CCDR</sub>	/CS ≥ V <sub>CC</sub> - 0.2 V	2.0		5.5	2.0		5.5	V
Data retention supply current	I <sub>CCDR</sub>	V <sub>CC</sub> = 3.0 V, /CS ≥ V <sub>CC</sub> - 0.2 V		0.5	20 <sup>Note1</sup>		0.5	7 <sup>Note2</sup>	μA
Chip deselection to data retention mode	t <sub>CDR</sub>		0			0			ns
Operation recovery time	t <sub>R</sub>		5			5			ms

**Notes** 1. 3 μA (T<sub>A</sub> ≤ 40 °C)

2. 2 μA (T<sub>A</sub> ≤ 40 °C), 1 μA (T<sub>A</sub> ≤ 25 °C)

**Data Retention Timing Chart**



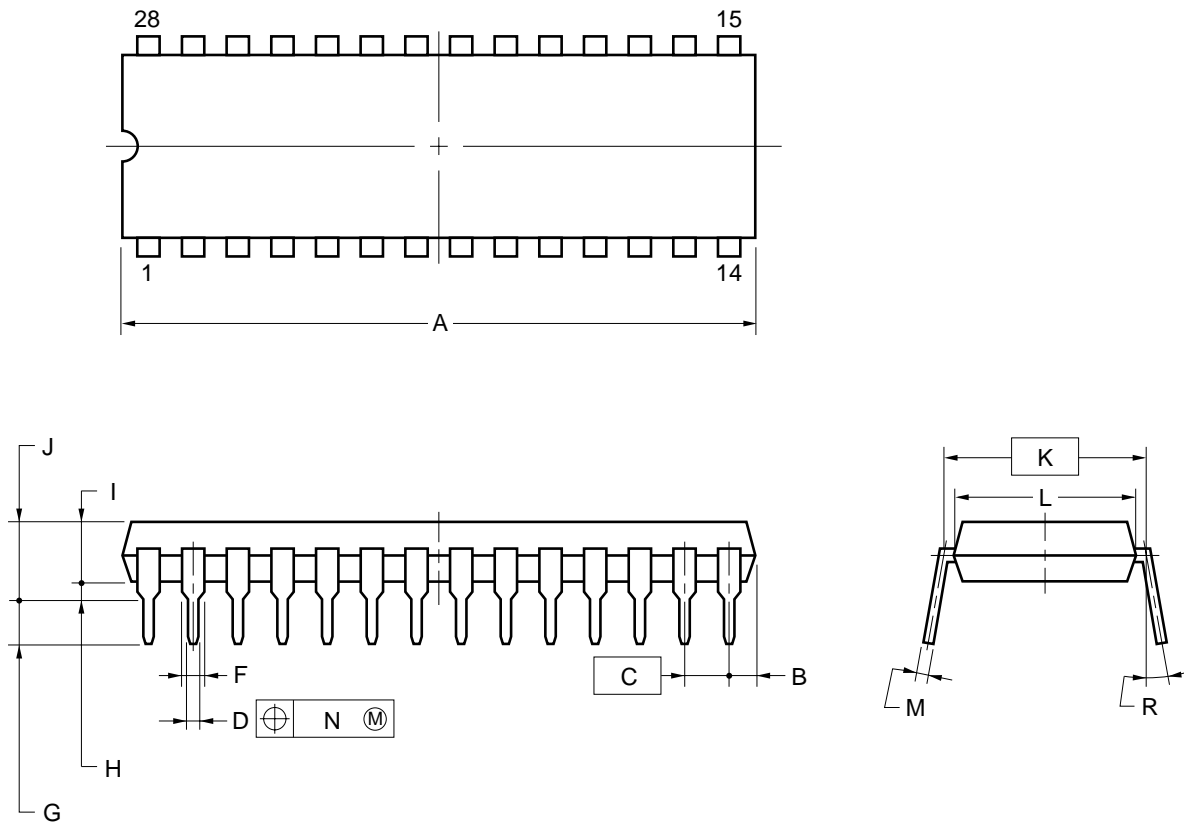
**Note** A version : 3.0 V, B version : 2.7 V

**Remark** The other pins (Address, /OE, /WE, I/O) can be in high impedance state.



Package Drawings

28-PIN PLASTIC DIP (15.24 mm (600))



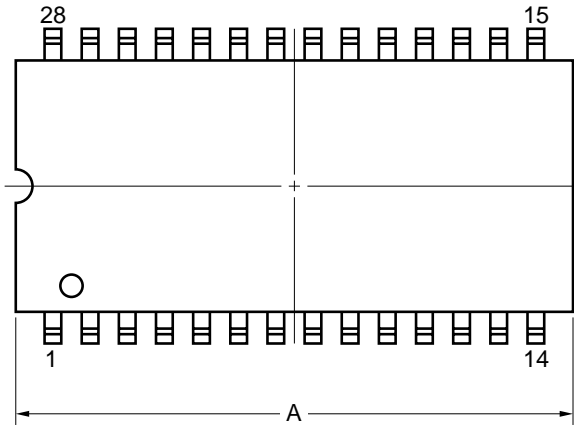
NOTES

1. Each lead centerline is located within 0.25 mm of its true position (T.P.) at maximum material condition.
2. Item "K" to center of leads when formed parallel.

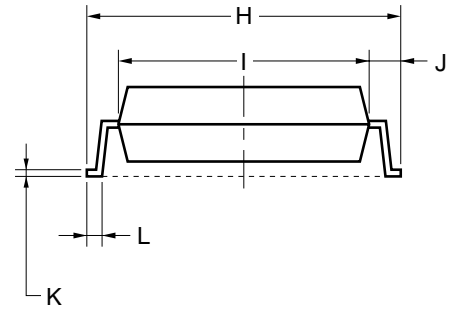
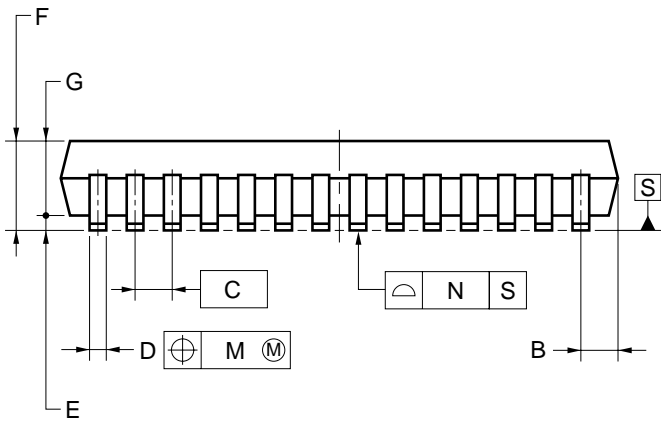
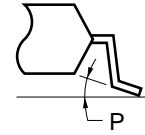
ITEM	MILLIMETERS
A	38.10 MAX.
B	2.54 MAX.
C	2.54 (T.P.)
D	0.50±0.10
F	1.2 MIN.
G	3.6±0.3
H	0.51 MIN.
I	4.31 MAX.
J	5.72 MAX.
K	15.24 (T.P.)
L	13.2
M	0.25 <sup>+0.10</sup> <sub>-0.05</sub>
N	0.25
R	0 - 15°

P28C-100-600A1-2

★ 28-PIN PLASTIC SOP (11.43 mm (450))



detail of lead end



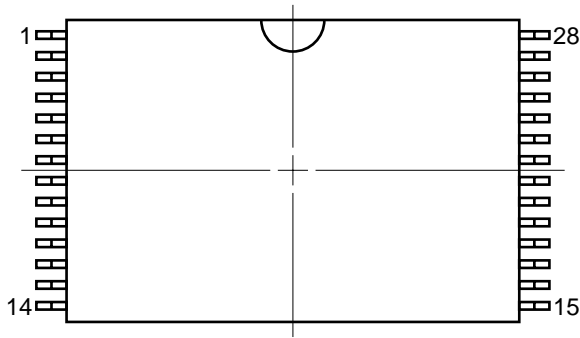
**NOTE**

Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

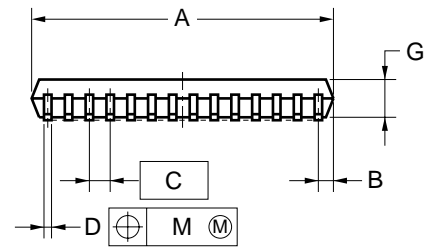
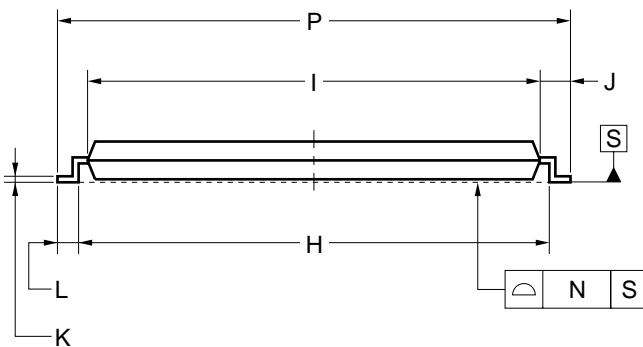
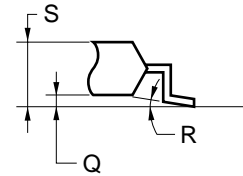
ITEM	MILLIMETERS
A	18.0 <sup>+0.6</sup> <sub>-0.05</sub>
B	1.27 MAX.
C	1.27 (T.P.)
D	0.42 <sup>+0.08</sup> <sub>-0.07</sub>
E	0.2±0.1
F	2.95 MAX.
G	2.55±0.1
H	11.8±0.3
I	8.4±0.1
J	1.7±0.2
K	0.22±0.05
L	0.7±0.2
M	0.12
N	0.10
P	3° <sup>+7°</sup> <sub>-3°</sub>

P28GU-50-450A-4

28-PIN PLASTIC TSOP(I) (8x13.4)



detail of lead end



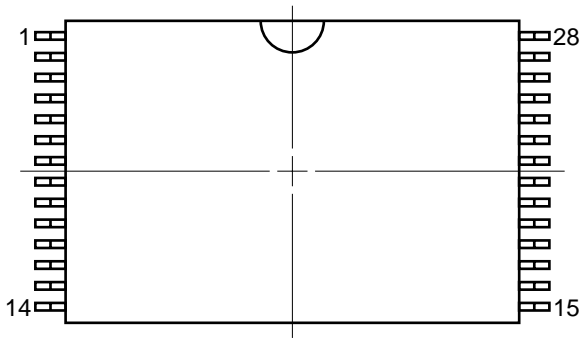
NOTES

1. Each lead centerline is located within 0.08 mm of its true position (T.P.) at maximum material condition.
2. "A" excludes mold flash. (Includes mold flash : 8.4mm MAX.)

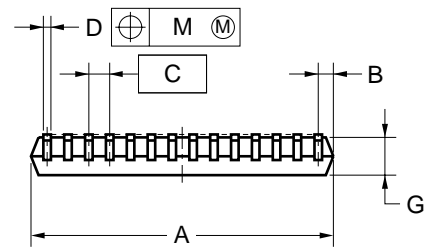
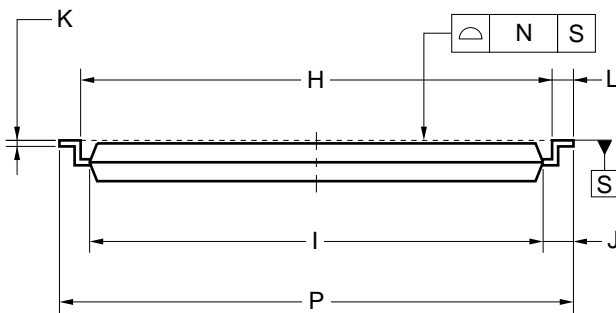
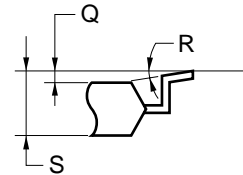
ITEM	MILLIMETERS
A	8.0±0.1
B	0.6 MAX.
C	0.55 (T.P.)
D	0.22 <sup>+0.08</sup> <sub>-0.07</sub>
G	1.0
H	12.4±0.2
I	11.8±0.1
J	0.8±0.2
K	0.145 <sup>+0.025</sup> <sub>-0.015</sub>
L	0.5±0.1
M	0.08
N	0.10
P	13.4±0.2
Q	0.1±0.05
R	3° <sup>+7°</sup> <sub>-3°</sub>
S	1.2 MAX.

P28GW-55-9JL-2

28-PIN PLASTIC TSOP(I) (8x13.4)



detail of lead end



NOTE

1. Each lead centerline is located within 0.08 mm of its true position (T.P.) at maximum material condition.
2. "A" excludes mold flash. (Includes mold flash : 8.4mm MAX.)

ITEM	MILLIMETERS
A	8.0±0.1
B	0.6 MAX.
C	0.55 (T.P.)
D	0.22 <sup>+0.08</sup> <sub>-0.07</sub>
G	1.0
H	12.4±0.2
I	11.8±0.1
J	0.8±0.2
K	0.145 <sup>+0.025</sup> <sub>-0.015</sub>
L	0.5±0.1
M	0.08
N	0.10
P	13.4±0.2
Q	0.1±0.05
R	3° <sup>+7°</sup> <sub>-3°</sub>
S	1.2 MAX.

P28GW-55-9KL-2

**Recommended Soldering Conditions**

The following conditions (See table below) must be met when soldering μPD43256B. For more details, refer to our document “**SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL**” (C10535E).

Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

**Types of Surface Mount Device**

- μPD43256BGU-xxL : 28-PIN PLASTIC SOP (11.43 mm (450))
- μPD43256BGU-xxLL : 28-PIN PLASTIC SOP (11.43 mm (450))
- μPD43256BGU-Axx : 28-PIN PLASTIC SOP (11.43 mm (450))
- μPD43256BGU-Bxx : 28-PIN PLASTIC SOP (11.43 mm (450))
- μPD43256BGW-xxLL-9JL : 28-PIN PLASTIC TSOP (I) (8x13.4) (Normal bent)
- μPD43256BGW-xxLL-9KL : 28-PIN PLASTIC TSOP (I) (8x13.4) (Reverse bent)
- μPD43256BGW-Axx-9JL : 28-PIN PLASTIC TSOP (I) (8x13.4) (Normal bent)
- μPD43256BGW-Axx-9KL : 28-PIN PLASTIC TSOP (I) (8x13.4) (Reverse bent)
- μPD43256BGW-Bxx-9JL : 28-PIN PLASTIC TSOP (I) (8x13.4) (Normal bent)
- μPD43256BGW-Bxx-9KL : 28-PIN PLASTIC TSOP (I) (8x13.4) (Reverse bent)

Please consult with our sales offices.

**Types of Through Hole Mount Device**

- μPD43256BCZ-xxL : 28-PIN PLASTIC DIP (15.24 mm (600))
- μPD43256BCZ-xxLL : 28-PIN PLASTIC DIP (15.24 mm (600))

Soldering process	Soldering conditions
Wave soldering (only to leads)	Solder temperature : 260 °C or below, Flow time : 10 seconds or below
Partial heating method	Terminal temperature : 300 °C or below, Time : 3 seconds or below (Per one lead)

**Caution Do not jet molten solder on the surface of package.**

[ MEMO ]

**NOTES FOR CMOS DEVICES****① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS**

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

**② HANDLING OF UNUSED INPUT PINS FOR CMOS**

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to  $V_{DD}$  or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

**③ STATUS BEFORE INITIALIZATION OF MOS DEVICES**

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

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